## Bill of Materials

**TI DESIGNS**

**TIDM-1WIREEEPROM**

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<th>Manufacturer</th>
<th>Manufacturer Part Number</th>
<th>Alternate Part</th>
<th>Altium Footprint</th>
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<tr>
<td>1</td>
<td>1</td>
<td>C1</td>
<td>22uF</td>
<td>CAP, AL, 22uF, 25V, +/-20%, TH</td>
<td>Panasonic</td>
<td>20SEP22M</td>
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<td>ML_500x500</td>
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<td>D1</td>
<td>Diode, Schottky, 800mA, 30V, SM</td>
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<td>CUS08F30, H3F</td>
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<td>RES, 1.00k ohm, 1%, 0.25W, TH</td>
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